



FOR IMMEDIATE RELEASE

EV Group Highlights Hybrid and Fusion Bonding, Layer Transfer and Maskless Lithography Technologies for Advanced Semiconductor Memory and Packaging at SEMICON Korea 2026

ST. FLORIAN, Austria, February 4, 2026—EV Group (EVG), a leading provider of innovative process solutions and expertise serving leading-edge and future semiconductor designs and chip integration schemes, today announced that it will showcase its latest solutions for heterogeneous integration, advanced packaging and fine-pitch wafer probe card manufacturing at SEMICON Korea 2026, taking place February 11-13 at the COEX Exhibition Center in Seoul. These solutions include EVG’s GEMINI® FB production wafer bonding systems, the EVG®40 D2W die-to-wafer overlay metrology system, the IR LayerRelease™ layer transfer technology platform and EVG’s high-throughput LITHOSCALE® XT maskless exposure system.

EVG’s tools and process solutions play a critical role in enabling manufacturing advances across multiple technology domains, including high-bandwidth memory (HBM) and other advanced memory devices, as well as advanced packaging and MEMS applications, including sensors and fine-pitch wafer probe card manufacturing. At SEMICON Korea 2026, EVG will also participate in two technical sessions focused on its IR LayerRelease and maskless exposure platforms. The company will exhibit in booth DS26.

“Technology companies and research institutes in Korea continue to play a pivotal role in driving innovation across the global semiconductor industry, especially in advanced memory, 3D integration, and packaging technologies,” stated Georg Berger, Regional Sales Manager, Asia/Pacific at EV Group. “EVG is proud to support our customers and partners in Korea with field-proven solutions and strong local application and service capabilities.

Justin Yun, General Manager of EV Group Korea, added, “Events like SEMICON Korea provide an important opportunity for us to showcase our latest advances in hybrid bonding, lithography and layer transfer, and to collaborate with industry leaders shaping the future of semiconductor manufacturing.”

Supporting High-Yield Hybrid Bonding for Advanced Memory and 3D Integration

Wafer-to-wafer (W2W) hybrid bonding is critical for enabling high-yield, scalable manufacturing of next-generation 3D NAND and DRAM, which demand sub-micron alignment accuracy and excellent bond strength. Die-to-wafer (D2W) hybrid bonding is an important enabler of chiplet integration, HBM stacks, and 3D system on chip (SoC) integration processes. EVG provides a complete hybrid bonding process flow for W2W bonding, as well as comprehensive support for D2W hybrid bonding, including surface preparation, cleaning, collective die transfer, and high-precision alignment capabilities. The recently announced EVG40 D2W provides highly accurate, in-line overlay metrology for D2W bonding—supporting real-time feedback loops that help customers maximize die placement accuracy and performance.

Maskless Exposure Lithography for Advanced Packaging and Probe Card Applications

EVG’s LITHOSCALE platform combines high-resolution stitch-free patterning with powerful digital lithography and high throughput to offer a compelling lithography solution for a variety of packaging and MEMS applications. These include fan-out wafer-level packaging (FOWLP) for AI and high-performance computing (HPC) devices, fine-pitch wafer probe cards, advanced imaging sensors, and die traceability for security and automotive applications. With its fast exposure speed, flexible data handling and scalable architecture, EVG’s MLE™ (maskless exposure) technology is ideally suited for production environments that demand high-resolution patterning and rapid design turns. The new LITHOSCALE XT system, which

provides up to a five-fold increase in throughput versus the previous industry benchmark LITHOSCALE system, brings digital lithography to heterogeneous integration high-volume-manufacturing applications.

Enabling Thin-Die Stacks with IR LayerRelease

EVG's IR LayerRelease technology is a fully front-end-compatible layer transfer technology that features an infrared (IR) laser that can pass through silicon, which is transparent to the IR laser wavelength. Coupled with the use of specially formulated inorganic layers, this technology enables laser-initiated release of any ultra-thin film or layer from silicon carriers with nanometer precision and the highest debonding throughput in the industry. As a result, IR LayerRelease eliminates glass substrates for advanced packaging and enables completely novel process flows for 3D-IC and 3D sequential integration applications—enabling hybrid and fusion bonding even of ultra-thin layers on silicon carriers.

Technical Talks at SEMICON Korea 2026

EVG is also participating in the SEMICON Korea SEMI Technology Symposium (STS) program this year with the following talks:

- **“High Throughput Digital Lithography Development Enables AI and HPC Device Integration”** (S1 Advanced Lithography Session, Wed., Feb. 11, 3:15-3:40pm, Room #307) – presented by Dr. Ksenija Varga, Business Development Manager
- **“EVG LayerRelease Technology – Key Innovations in Carrier Systems: Addressing D2W and W2W Stacking Requirements”** (S6 Advanced Packaging Session, Thu., Feb. 12, 5:25-5:50pm, Room #317) – presented by Dr. Thomas Uhrmann, Vice President of Sales

Meet EVG at SEMICON Korea 2026

To speak with an EVG representative and learn more about the company's industry-leading solutions for hybrid bonding, maskless lithography, and ultra-thin layer transfer, visit EVG's booth DS26 during exhibition hours.

About EV Group (EVG)

EV Group (EVG) provides innovative process solutions and expertise that serve leading-edge and future semiconductor designs and chip integration schemes. The company's vision of being the first in exploring new techniques and supporting next-generation applications of micro- and nanofabrication technologies enables customers to successfully commercialize new product ideas. EVG's high-volume-manufacturing-ready products, which include wafer bonding, lithography, thin-wafer processing and metrology equipment, enable advances in semiconductor front-end scaling, 3D integration and advanced packaging, as well as in other electronics and photonics applications. More information about EVG is available at www.EVGroup.com.

Contacts:

Clemens Schütte
Director, Marketing and Communications
EV Group
Tel: +43 7712 5311 0
E-mail: Marketing@EVGroup.com

David Moreno
Principal
Open Sky Communications
Tel: +1.415.519.3915
E-mail: dmoreno@openskypr.com

###